PART NO.: HFJ14-1G01ERL

ROMS

1X4 FASTJACK™ WITH 1000BASE-T MAGNETICS DESIGNED FOR IEEE802.3ab APPLICATIONS

RoHS COMPLIANT

COMPATIBLE TO LEAD-FREE WAVE SOLDERING PROCESS FOR THROUGH HOLE COMPONENTS OPERATING TEMPERATURE 0/70°C

ELECTRICAL SPECIFICATIONS @25° C

1:1 ±3% TURNS RATIO OCL (100KHz,0.1V,8mA) 350µH min INSERTION LOSS 1-100MHz -1.1dB max RETURN LOSS 1-40MHz -18dB min 60MHz -14dB min 80MHz -12dB min 100MHz -10dB min CROSSTALK 1-100MHz -35dB typ CMR 1-30MHz -50dB typ 30-60MHz -40dB typ -35dB typ 60-100MHz 1.500Vrms **ISOLATION**

Housing Material: Polyester, Black UL94V-O Contacts: Phosphor Bronze 30µin Au

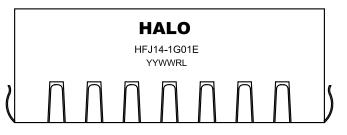
plating over Ni

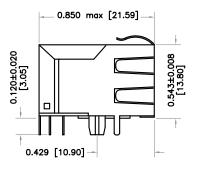
Leads: Matte Sn over Ni

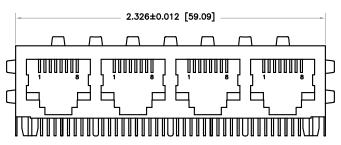
Shield: Cu Alloy with Ni plating 40 μ in min

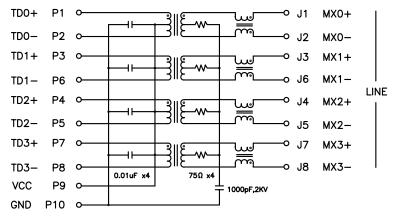
Durability: 1000 mating cycles Dimensions: Inch [mm]

Tolerances: ±0.008 inch if not specified







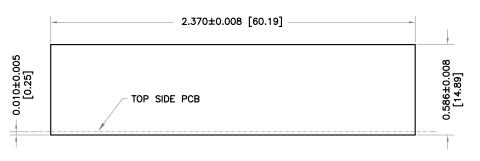




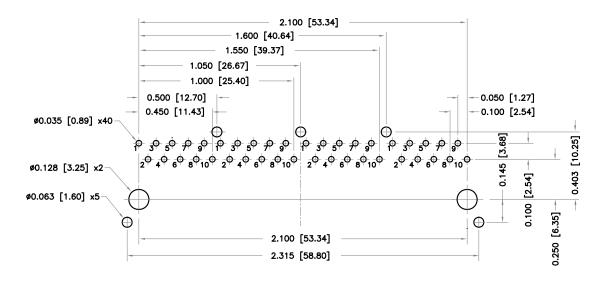
CALIFORNIA, USA KOWLOON, HONG KONG SINGAPORE

TITLE	^{ITLE} FastJack™ 1x4			SIGNATURES		DATE	REV.	DATE	DATE
FOR	FOR GIGABIT ETHERNET			DRAWN	PETER LU	7/4/06	Α	FIRST ISSUE	7/4/06
				CHECKED	LEI KEONG	8/8/06	В	PROD. RELEASE	8/8/06
PART NO. HFJ14-1G01ERL			APPROVED	PETER LU	8/8/06				
SCALE	NONE	PAGE	1 of 2	FILE	FJ141G01ERL.DWG				





RECOMMENDED PANEL CUTOUT DIMENSIONS: Inch [mm]



RECOMMENDED P.C. BOARD PATTERN (COMP. SIDE) TOLERANCES: ±0.002 [0.05] UNLESS SPECIFIED

HAI	LO/	PBI	
ПАІ	LUI	ГОІ	

CALIFORNIA, USA KOWLOON, HONG KONG SINGAPORE

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	SCALE	NONE	PAGE	2 of 2	FILE	FJ141G01ERL.DWG				

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